

ELECTRONIC PACKAGE FOR ELECTRONIC COMPONENTS AND METHOD OF MAKING SAME

ABSTRACT

An electronic package (10) and method of making the electronic package is provided. The package (10) includes a semiconductor chip (12) and an multi-layered interconnect structure (18). The semiconductor chip (12) includes a plurality of contact members (16) on one of its surfaces (14) that are connected to the multi-layered interconnect structure (18) by a plurality of solder connections (47). The multi-layered interconnect structure (18) is adapted for electrically interconnecting the semiconductor chip (12) to a circuitized substrate (100) (eg., circuit board) with another plurality of solder connections (20) and includes a thermally conductive layer (22) being comprised of a material having a selected thickness and coefficient of thermal expansion to substantially prevent failure of the solder connections between said first plurality of electrically conductive members and the semiconductor chip (12). The electronic package (10) further includes a dielectric material having an effective modulus to assure sufficient compliancy of the multi-layered interconnect structure (18) during operation.

Fig.1



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